



Polymers as a Springboard in Material Sciences: From Insulating Protective Coatings to Conducting Smart Films

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Message from the Guest Editors

Dear Colleagues,

The Special Issue will explore polymeric films/coatings based on novel materials (possibly sustainable and green) and/or be employed in innovative applications (including renewable energy ones, biomedical and sensing devices). A non-exhaustive list of acceptable topics may include the following:

- Polymeric films in devices (photoelectrochemical ones, smart windows, etc.);
- Polymers as chemically active surfaces;
- Polymer films in sensors (e.g., electrochemical ones);
- Polymeric coatings for corrosion protection;
- Polymeric coatings in the food industry;
- Smart polymeric coatings;
- Polymer composite films/coatings;
- Molecularly imprinted polymer films;
- Chiral conductive polymers;
- Polymers in spintronics;
- Polymer films in bipolar electrochemistry (e.g., actuators);
- Polymers in medical and biomedical devices.

This Special Issue could be helpful for the broad chemistry community working on polymeric coatings and films.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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